TOSHIBA Photocoupler IRED & Photo IC

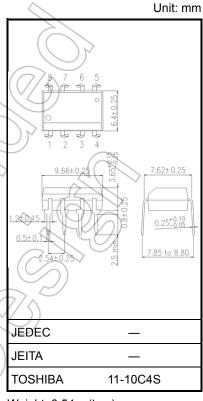
TLP552

Isolated Line Receiver
Simplex/Multiplex Data Transmission
Computer-Peripheral Interface
Microprocessor System Interface
Digital Isolation for A-D, D-A Conversion

The TOSHIBA TLP552 is a photocoupler which combines an infrared emitting diode and an integrated high gain, high speed photodetector. This unit is 8-lead DIP.

The output of the detector circuit is an open collector, Schottky clamped transistor.

- TTL/LSTTL compatible: $V_{CC} = 5 \text{ V}$
- Isolation voltage: 2500 V_{rms} (min)
- Switching speed: t_{pHL} , $t_{pLH} = 60$ ns (typ.) (@R_L = 350 Ω)
- Guaranteed performance over temp.: 0 to 70°C
- UL-recognized: UL 1577, File No.E67349



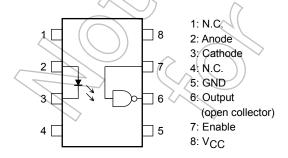
Weight: 0.54 g (typ.)

Truth Table (positive logic)

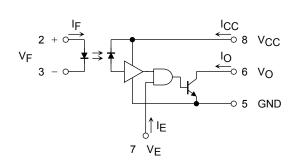
Input	Enable	Output
Н	Н	
L	Н	TH TH
Н		()) н
L	// L)	H

Note: A 0.1 µF bypass capacitor must be connected between pins 8 and 5 (see "Instruction for use" on page 3).

Pin Configurations (top view)



Schematic



Note: A 0.1 μF bypass capacitor must be connected between pins 8 and 5 (see "Instruction for use" on page 3)

Start of commercial production 1982-08

Absolute Maximum Ratings (Ta = 25°C)

	Characteristics	Symbol	Rating	Unit
	Forward current	l _F	20	mA
	Forward current derating (Ta ≥ 53°C)	∆IF/∆Ta	-0.28	mA/°C
	Pulse forward current (Note 1)	IFP	40	mA
LED	Peak transient forward current (Note 2)	IFPT	0.5	Α (
	Reverse voltage	V _R 5		V
	Diode power dissipation	P_{D}	40	mW
	Input power dissipation derating(Ta ≥ 53°C)	ΔP _D /°C	-0.56	mW/°C
	Output current	IO	50	mA
	Output voltage	VO	7	
ctor	Supply voltage (Note 3)	V _{CC}	7	V
Detector	Enable input voltage (Note 4)	٧E	5.5	V
	Output collector power dissipation	PO	85	mW
	Output power dissipation derating (Ta ≥ 53°C)	ΔΡο/ ΔΤα	(1.2)	mW/°C
Оре	erating temperature range	Topr	0 to 70	°C
Storage temperature range		T _{stg}	-55 to 125	°¢C
Lea	d solder temperature (10 s) (Note 5)	T _{sol}	260	°C
Isola	ation voltage (AC, 60 s, R.H. ≤ 60 %) (Note 6)	BVS	2500	V _{rms}

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

- Note 1: 50 % duty cycle, 1 ms pulse width.
- Note 2: Pulse width $\leq 1 \mu s$, 300 pps.
- Note 3: 1 minute maximum.
- Note 4: Not to exceed VCC by more than 500 mV.
- Note 5: Soldering portion of lead: up to 2 mm from the body of the device.
- Note 6: Device considered a two-terminal device: Pins 1, 2, 3 and 4 shorted together, and pins 5, 6, 7 and 8 shorted together.

Recommended Operating Conditions

_ ^					
Characteristics	Symbol	Min	Тур.	Max	Unit
Input current, low level	Y JPL	0	_	250	μА
Input current, high level	lFH	7	-	20	mA
Supply voltage, output	Vcc	4.5	-	5.5	٧
High level enable voltage	VEH	2.0	١	Vcc	>
Low level enable voltage	VEL	0	_	0.8	٧
Fan out (TTL load)	N	_	_	8	_
Operating temperature	T _{opr}	0	_	70	°C

Note: The recommended operating conditions are given as a design guideline to obtain expected performance of the device. In addition, each item is an independent guideline. In developing designs using this product, please confirm the specified characteristics shown in this document.

Electrical Characteristics (unless otherwise specified, for $0^{\circ}C \le Ta \le 70^{\circ}C$)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input forward voltage	V _F	I _F = 10 mA, Ta = 25 °C	_	1.65	1.8	V
Input diode temperature coefficient	ΔV _F /ΔTa	I _F = 10 mA	_	-2.0	_	mV/°C
Input reverse current	I _R	V _R = 5 V, Ta = 25 °C		_	10	μΑ
Input capacitance	C _T	V _F = 0 V, f = 1 MHz, Ta = 25 °C		45	_	pF
High level output current	ІОН	V _{CC} = 5.5 V, V _O = 5.5 V I _F = 250 µA, V _E = 2.0 V		10	250	μΑ
Low level output voltage	V _{OL}	$V_{CC} = 5.5 \text{ V}, I_F = 5 \text{ mA}$ $V_{EH} = 2.0 \text{ V}, I_{OL} = 13 \text{ mA}$ (sinking)	9)_	0.4	0.6	V
Input current logic low output level	lFH	I _{OL} = 13 mA (sinking), V _O = 0.6 V, V _{CC} = 5.5 V, V _{EH} = 2.0 V			5	mA
High level enable current	I _{EH}	V _{CC} = 5.5 V, V _E = 2.0 V	-/2	-1.0	_	mA
Low level enable current	IEL	V _{CC} = 5.5 V, V _E = 0.5 V	Θ)-1.6	-2.0	mA
High level supply current	Іссн	$V_{CC} = 5.5 \text{ V}, I_F = 0 \text{ mA}, V_E = 0.5 \text{ V}$	(- T	(7)/	15	mA
Low level supply current	ICCL	V _{CC} = 5.5 V, I _F = 10 mA, V _E = 0.5 V	7	12	18	mA
Current transfer ratio	CTR	$I_F = 5.0 \text{ mA}, R_L = 100 \Omega$ $V_{CC} = 5.0 \text{ V}, T_A = 25 ^{\circ}\text{C}$	2)	1000	_	%
Resistance (input-output)	RS	V _S = 500 V, R.H. ≤ 60 %, Ta = 25 °C	5 × 10 ¹⁰	10 ¹⁴	_	Ω
Capacitance (input-output)	C _S	V _S = 0 V, f = 1 MHz, Ta = 25 °C	_	0.6	_	pF

Note: All typical values are at Ta = 25 °C

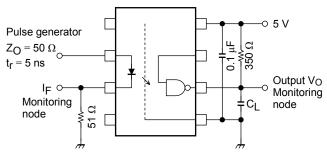
Switching Characteristics ($Ta = 25^{\circ}C$, $V_{CC} = 5 \text{ V}$)

Characteristics	Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit
Propagation delay time to high output level (L \rightarrow H)	tpLH	1	$R_L = 350 \Omega$, $C_L = 15 pF$ $T_F = 7.5 mA$	_	60	120	ns
Propagation delay time to low output level (H → L)	t _{pHL}	1	$R_L = 350 \Omega$, $C_L = 15 pF$ $I_F = 7.5 mA$	ı	60	120	ns
Output rise fall time (10 to 90%)	t _r , t _f	1	R _L = 350 Ω , C _L = 15 pF I _F = 7.5 mA	_	30	_	ns
Propagation delay time of enable from VEH to VEL	teLH .	2	$R_L = 350 \Omega$, $C_L = 15 pF$ $I_F = 7.5 mA$, $V_{EH} = 3.0 V$	-	25	_	ns
Propagation delay time of enable from VEL to VEH	t _{EHL}	2	$R_L = 350 \Omega$, $C_L = 15 pF$ $I_F = 7.5 mA$, $V_{EH} = 3.0 V$	-	25	_	ns
Common mode transient immunity at logic high output level	CMH	3	$V_{CM} = 200 \text{ V}, R_L = 350 \Omega$ $V_{O} \text{ (min)} = 2 \text{ V}, I_F = 0 \text{ mA}$	- 1	200		V / μs
Common mode transient immunity at logic low output level	CML	3	$V_{CM} = 200 \text{ V}, R_L = 350 \Omega$ $V_{O} \text{ (max)} = 0.8 \text{ V}, I_F = 5 \text{ mA}$	_	-500	_	V / μs

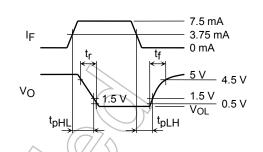
Instruction for use

1. A ceramic capacitor $(0.1 \, \mu F)$ should be connected from pin 8 and pin 5 to stabilize the operation of the high gain linear amplifier. Failure to provide the bypassing may impair the switching properties. The total lead length between the capacitor and coupler should not exceed 1 cm.

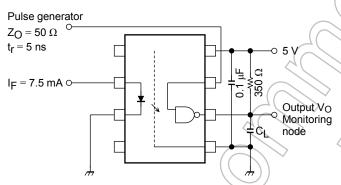
Test Circuit 1: Switching Time Test Circuit



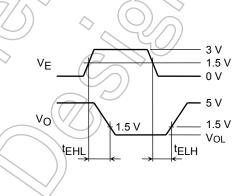
 $\ensuremath{\text{C}_{L}}$ is approximately 15 pF which includes probe and stray wiring capacitance.



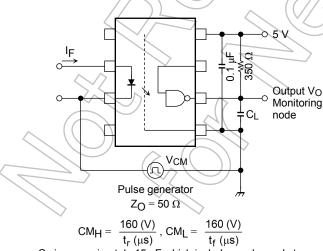
Test Circuit 2: Switching Time Test Circuit



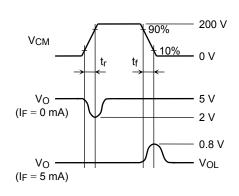
C_L is approximately 15 pF which includes probe and stray wiring capacitance.



Test Circuit 3: Common Mode Noise Immunity Test Circuit

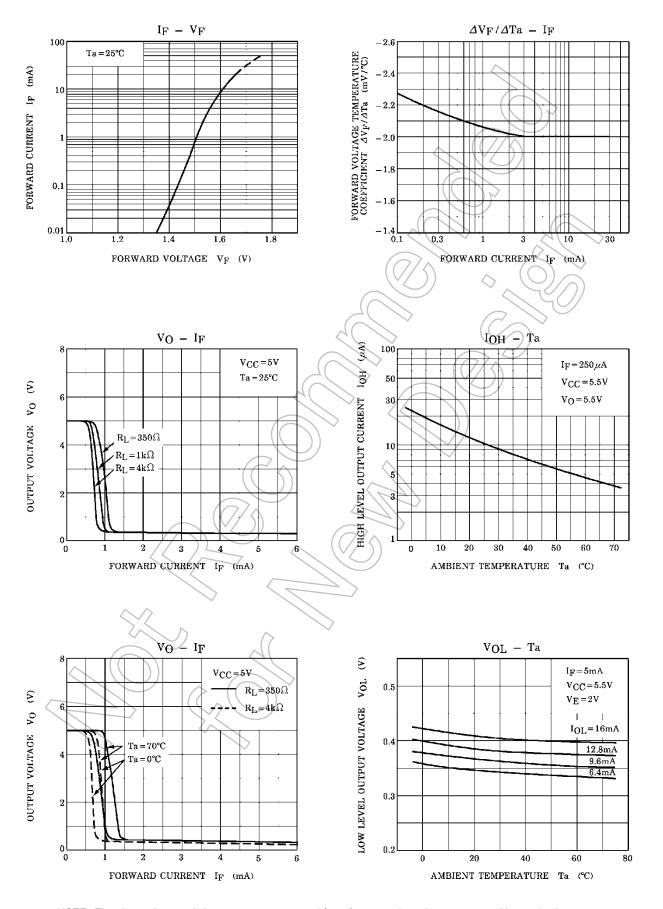


C_L is approximately 15 pF which includes probe and stray wiring capacitance.

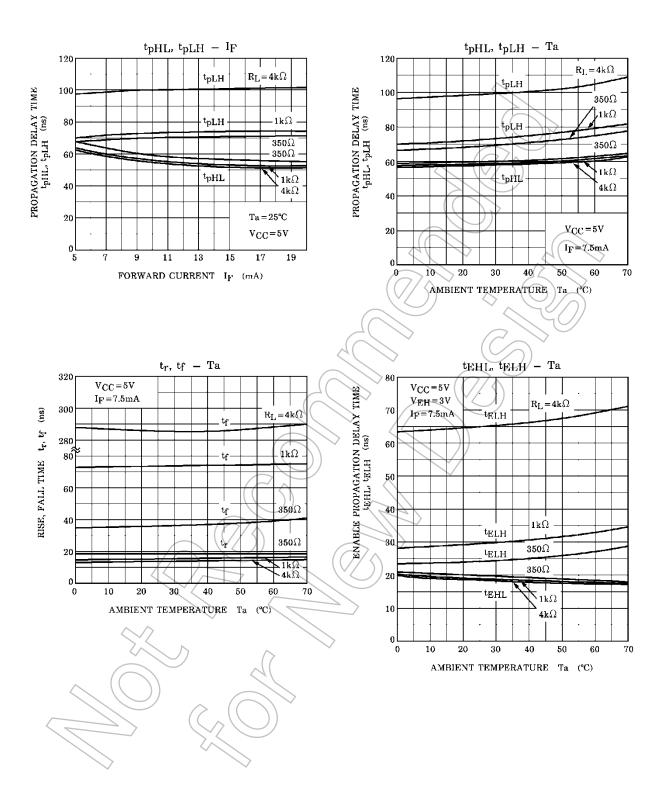


CMH: The maximum tolerable rate of rise of the common mode voltage to ensure the output will remain in the high output state (i.e., $V_O > 2.0 \text{ V}$). Measured in volts per microsecond (V / μ s).

CML: The maximum tolerable rate of fall of the common mode voltage to ensure the output will remain in the low output state (i.e., $V_O < 0.8 \ V$). Measured in volts per microsecond (V / μs).



NOTE: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



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